



SOT762-1

plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | DHVQFN14 |
| Package type industry code | DHVQFN14 |
| Package style descriptive code | DHVQFN (DIL-compatible thermal enhanced very thin quad flatpack; no leads) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| IEC package outline code | --- |
| JEDEC package outline code | MO-241 |
| JEITA package outline code | --- |
| Mounting method type | S (surface mount) |
| Issue date | 5-5-2015 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-----|-----|------|
| D | package length | 2.9 | - | 3 | 3.1 | mm |
| E | package width | 2.4 | - | 2.5 | 2.6 | mm |
| A | seated height | [tbd] | - | - | 1 | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 14 | - | |

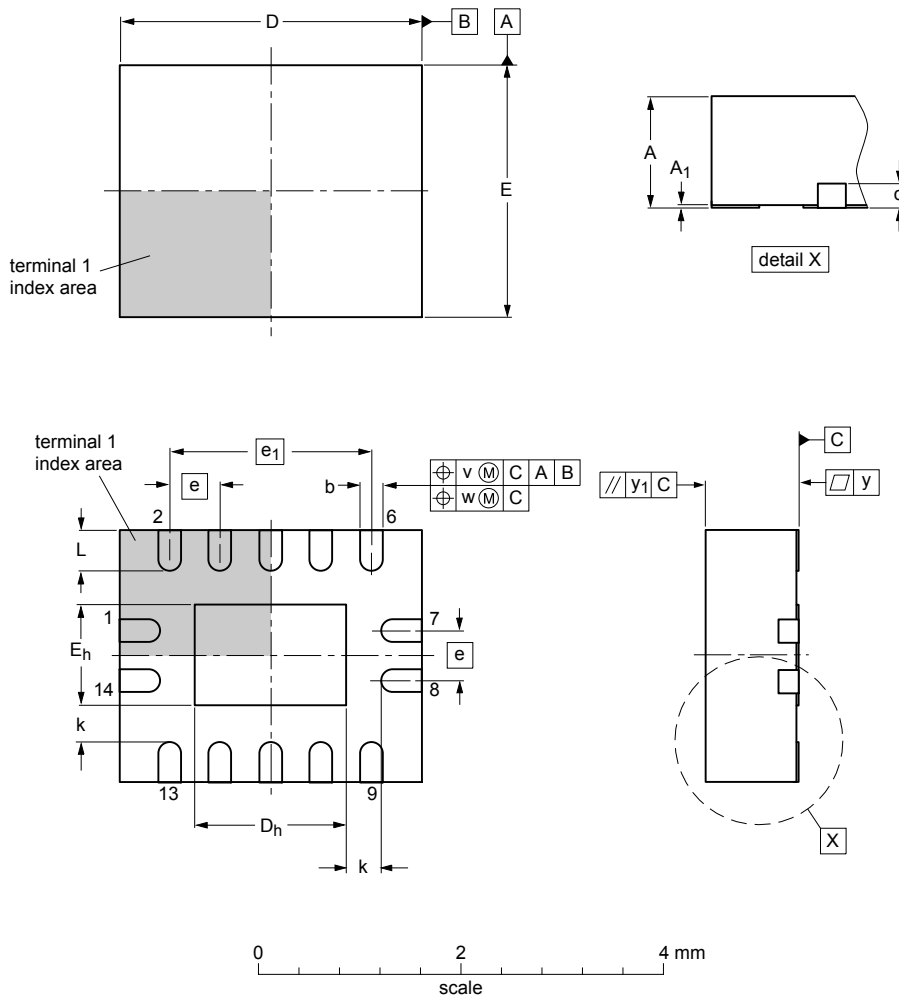


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2. Package outline

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

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Dimensions (mm are the original dimensions)

| Unit | A ⁽¹⁾ | A ₁ | b | c | D ⁽¹⁾ | D _h | E ⁽¹⁾ | E _h | e | e ₁ | k | L | v | w | y | y ₁ |
|------|------------------|----------------|------|-----|------------------|----------------|------------------|----------------|-----|----------------|-----|-----|-----|------|------|----------------|
| max | 1 | 0.05 | 0.30 | | 3.1 | 1.65 | 2.6 | 1.15 | | | | 0.5 | | | | |
| nom | | 0.02 | 0.25 | 0.2 | 3.0 | 1.50 | 2.5 | 1.00 | 0.5 | 2 | | 0.4 | 0.1 | 0.05 | 0.05 | 0.1 |
| min | | 0.00 | 0.18 | | 2.9 | 1.35 | 2.4 | 0.85 | | | 0.2 | 0.3 | | | | |

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot762-1_po

| Outline version | References | | | European projection | Issue date |
|-----------------|------------|--------|-------|---------------------|------------------------|
| | IEC | JEDEC | JEITA | | |
| SOT762-1 | | MO-241 | | | -15-04-10- 15-05-05 |

Fig. 1. Package outline DHVQFN14 (SOT762-1)

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3. Soldering

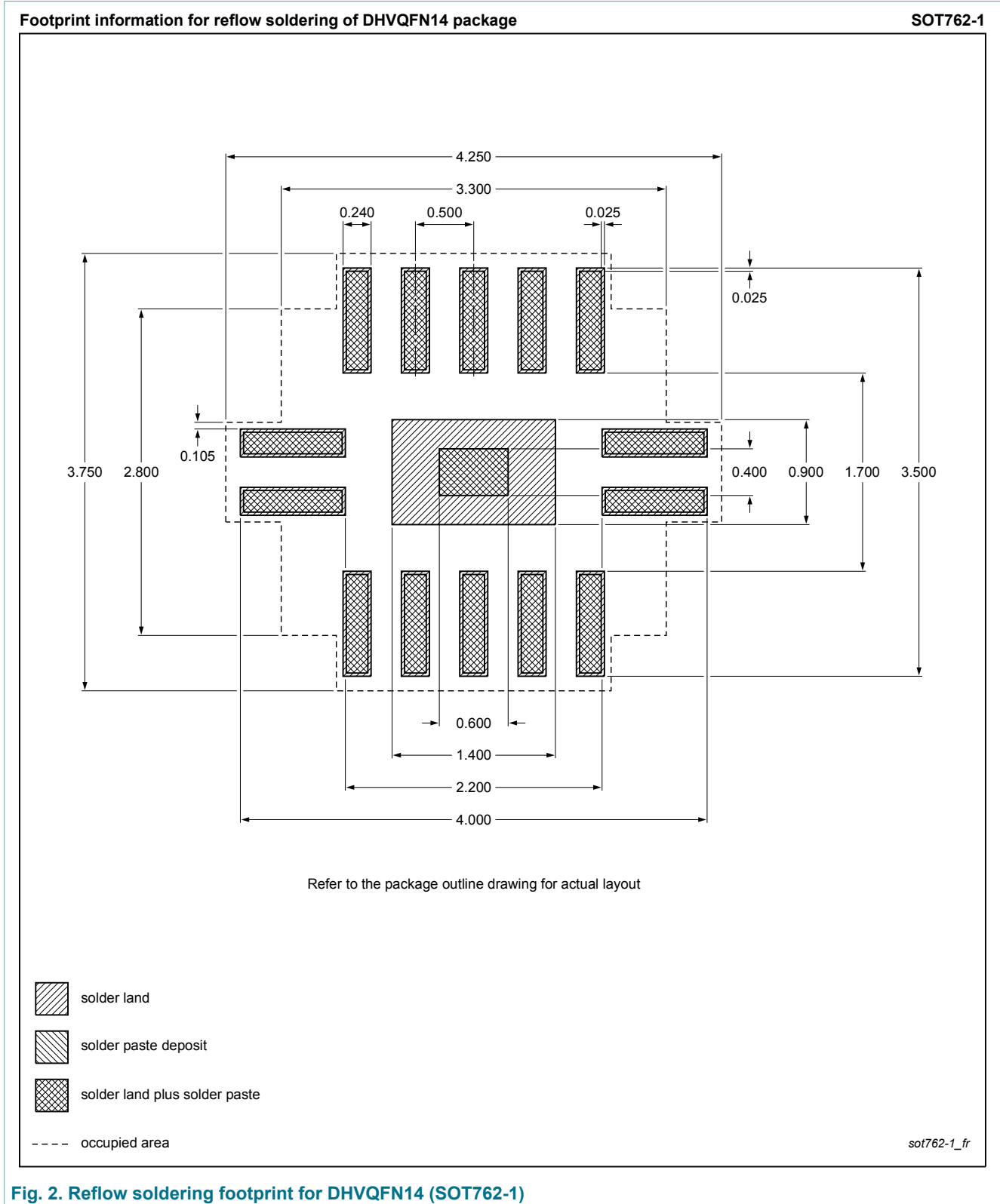


Fig. 2. Reflow soldering footprint for DHVQFN14 (SOT762-1)

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4. Legal information

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